

Application Serial No. 10/649,212
Reply to Office Action of September 27, 2007

PATENT
Docket: CU-5984

Amendments to the Specification

Please replace the abstract with the following amended abstract:

~~It is a main object of the present invention to provide a method for manufacturing conductive pattern capable of forming a highly precise pattern, also capable of forming by using a simple process, and being free from problems such as treatment of waste fluids. In order to attain the above object, the present invention provides~~ A ~~method for manufacturing a conductive pattern forming body comprising including: a pattern forming body substrate preparing process of preparing pattern forming body substrate comprising~~ having ~~a base material, and a photocatalyst containing layer formed on the base material comprising~~ having ~~a photocatalyst and a binder whose wettability of an energy irradiated part is changed so as a contact angle to a liquid is reduced; a wettability pattern forming process of forming wettability pattern comprising~~ having ~~a liquid repellent area and a lyophilic area on the photocatalyst containing layer by irradiating the photocatalyst containing layer in a pattern with energy; a metal colloid coating process of adhering a metal colloid only to the lyophilic area of the surface of the photocatalyst containing layer on which the wettability pattern is formed, by coating the metal colloid; and a conductive pattern forming process of forming conductive pattern by solidifying the metal colloid adhered to the lyophilic area of the wettability pattern.~~